PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS:    Andreas NEYER ET AL - 1 (PCT)

PCT NO.:       PCT/DE2004/002242

FILED:         OCTOBER 8, 2004

SERIAL NO.:    10/575,125

TITLE:         METHOD FOR THE PRODUCTION OF ELECTROOPTICAL
               PRINTED CIRCUIT BOARDS COMPRISING POLYSILOXANE
               WAVE GUIDES AND USE THEREOF

## INFORMATION DISCLOSURE STATEMENT

**MAIL STOP PCT**
Commissioner of Patents
P.O. Box 1450
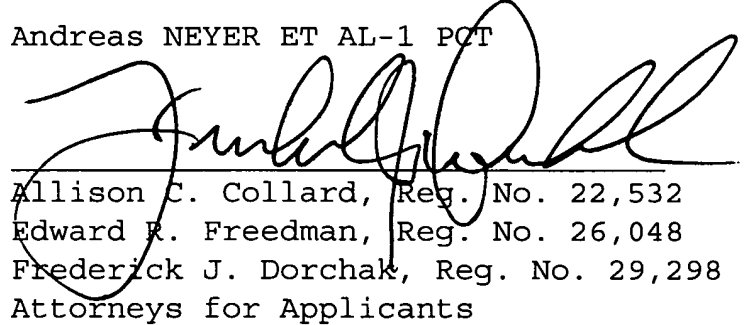Alexandria, VA   22313-1450

Dear Sir:

Applicants are enclosing Form PTO-1449 listing references cited in the International Search Report, copy enclosed, or in the Specification.  Copies of the U.S. references are not enclosed herewith, pursuant to current U.S.P.T.O. guidelines. "*S. Lechmacher, A. Neyer, "Integration of polymer optical waveguides into printed circuit boards (PCB)...*" was discussed in the Specification on page 2. *US 2003/0006068 A1* was discussed in the Specification on page 4. *US 2003/0007745 A1* was discussed in the Specification on page 5.

Because the instant Information Disclosure Statement is being filed before the issuance of a first office action, it is believed that no official fee is required in connection with the same.  It is respectfully requested that the foregoing Information Disclosure

Statement be incorporated into the official file of the
concurrently-filed PCT patent application.

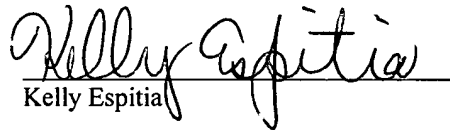Respectfully submitted,

Andreas NEYER ET AL-1 PCT

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Enclosures:  PTO-1449 form, International Search Report and 4 references

| FORM PTO-1449<br>(REV. 7-80) | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE | ATTY. DOCKET NO. :<br>NEYER ET AL-1 PCT | SERIAL NO. |
|---|---|---|---|
| **LIST OF REFERENCES CITED BY APPLICANT**<br><br>(Use several sheets if necessary) | | APPLICANT:Andreas NEYER et al. | |
| | | FILING DATE: | GROUP: |

### U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|---|---|---|---|---|---|---|---|
| | AA | 6,088,492 A | 07/2000 | Kaneko et al (ISR) | | | |
| | AB | 2003/108269 A1 | 06/2003 | Pogge et al. (ISR) | | | |
| | AC | 2003/179979 A1 | 09/2003 | Ouchi (ISR) | | | |
| | AD | 2003/0006068 A1 | 01/2003 | Tourne (Spec) | | | |
| | AE | 2003/0007745 A1 | 01/2003 | Martwick (Spec) | | | |

### FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION YES | NO |
|---|---|---|---|---|---|---|---|---|
| | AL | EP 1 142 682 A | 10/2001 | European (ISR) | | | | |
| | AM | | | | | | | |

### OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

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| | AR | | Kopetz S. et al: "Coupling of optoelectronic modules to optical layer in printed circuit boards (PCBs)" PROCEEDINGS OF THE SPIE-THE INTERNATIONAL SOCIETY FOR OPTICAL ENGINEERING SPIE-INT. SOC. OPT. ENG USA vol. 4942, 30 October 2002 (2002-10-30), pages 282-286, XP002315409 ISSN: 0277-786X (ISR) (Enclosed) |
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| | AS | | Griese E. et al: "Self-aligned coupling of optical transmitter and receiver modules to board-integrated optical multimode waveguides" PROCEEDINGS OF THE SPIE - THE INTERNATIONAL SOCIETY FOR OPTICAL ENGINEERING SPIE-INT. SOC. OPT. ENG USA, vol. 4455, 29 July 2001 (2001-07-29), pages 243-250, XP002315410 ISSN: 0277-786X (ISR) |
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| | AT | | Lehmacher S. et al: "Integration of Polymer Optical Waveguides Into Printed Circuit Boards (PCB)" Proceedings. Micro. Tec. VDE World Microtechnologies Congress, PROCEEDINGS OF INTERNATIONAL CONFERENCE ON MICROTECHNOLOGIES, XX, XX, 25 September 2000 (2000-09-25), pages 111-113, XP001035010 (ISR and Spec) (Enclosed) |
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| EXAMINER | DATE CONSIDERED |
|---|---|
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.